Akrometrix LLC
2700 Northeast Expressway NE
Building B, Suite 500
Atlanta, GA 30345
404-486-0880
Web Site: www.akrometrix.com

FOR IMMEDIATE RELEASE

CONTACT:
Akrometrix
Eric J. Moen, Vice President of Sales & Marketing
404-486-0880 x21
E-mail: EMoen@akrometrix.com

Akrometrix to Participate in the SMTAI Spotlight 5 Panel Discussion: "Warpage Induced Defects and Component Warpage Limits"

ATLANTA, GA — August 2017 — Akrometrix, LLC, the leading provider of thermal warpage and strain metrology equipment to both the front- and back-end semiconductor and electronics industries, announces that Neil Hubble, Director of Engineering, will be a panelist in the upcoming SMTAI Spotlight 5 panel discussion, scheduled to take place Wednesday, Sept. 10, 2017 from 2-3 p.m. The discussion, entitled "Warpage Induced Defects and Component Warpage Limits," will be streamed on Facebook Live.

The Spotlight 5 session will be chaired by Brook Sandy-Smith of Indium Corporation and co-chaired by Eric Moen of Akrometrix. It will feature experts and distinguished speakers who have experience in mitigating thermal warpage in many different areas of the assembly process, including PCB and component design, PCB and soldering materials, assembly and package connectivity, and inspection/metrology. Neil Hubble will lend his expertise regarding current thermal metrology methods for measuring coplanarity as well as current standards and new challenges for identifying warpage sign and shape on 3D packages. Other panelists include Alex Chan of Nokia, Martin Anselm, Ph.D., of Rochester Institute of Technology (RIT), Raiyo F. Aspandiar, Ph.D., of Intel Corporation and Dale E. Lee of Plexus Corp.

The abstract for the panel states: Warpage induced defects have been a hot topic for a long time, but the drive toward miniaturization as well as the drive for miniaturized systems-in-package are creating a host of new thermal warpage challenges. The next generation of BGAs, sockets, connectors, SiP, PoP and LGA components have even more challenges due to thinning dimensions, changing materials and packaging processes, and growing package complexity. This goes far beyond the traditional head-in-pillow defects and smile/frown warpage. Dynamic warpage and components designed to be flat at reflow temps are revealing new sources of warpage induced stress. Developing strategies such as low temperature soldering also lead to new challenges and material trade-offs. Join us for this panel discussion in which our panel of experts will be prepared to drill-down on causes and solutions to many of these challenges.

Akrometrix, LLC is pleased to participate in a panel discussion which will bring expert discussion and advice regarding a wide spectrum of challenges relating to thermal warpage.

For more information about Akrometrix, please contact sales@akrometrix.com or visit www.akrometrix.com.

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About Akrometrix LLC

Akrometrix is the leader in thermal warpage and strain metrology for the front-end/back-end wafer, back-end packaging/assembly, panel and the PCB/component markets. The company provides both capital equipment and test services to measure warpage and strain in temperatures from -50°C to 300°C on virtually any substrate up to 600mm x 600mm, regardless of shape. Located in Atlanta, Georgia, Akrometrix has been serving customers worldwide for more than 20 years based on technology developed at Georgia Tech. For more information, contact Akrometrix at sales@Akrometrix.com or visit www.akrometrix.com.

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